

Applicant: Andrew Holland
Serial No.: Unassigned
Filing Date: Herewith
Docket No.: 1662-2 PCT/US
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IN THE SPECIFICATION:

Please amend the title as follows:

~~IMPROVEMENTS IN OR RELATING TO ELECTRONICS PACKAGING~~
SEMICONDUCTOR PACKAGE WITH INTEGRATED HEATSINK AND
ELECTROMAGNETIC SHIELD

Please add the following immediately after the title of the invention:

CROSS-REFERENCE TO RELATED APPLICATIONS:

This application is the National Stage of International Application No. PCT/GB2004/005217, filed on December 17, 2004, which claims priority to GB Application No. 0329351.1, filed on December 18, 2003, and GB Application No. 0423172.6, filed on October 19, 2004, the contents of which is incorporated by reference herein.

Please add the following new paragraph immediately prior to page 1, line 4, and after the Cross Reference to Related Applications, as follows:

FIELD OF THE INVENTION:

Please add the following new paragraph immediately prior to page 1, line 9, as follows:

BACKGROUND OF THE INVENTION:

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Please add the following new paragraph immediately prior to page 10, line 14, as follows:

BRIEF DESCRIPTION OF THE DRAWINGS:

Please add the following new paragraph immediately prior to page 16, line 6, as follows:

DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS:

Please amend the section description for the claims on the top of page 42, as follows:

CLAIMS WHAT IS CLAIMED IS: